

Purpose

This declaration is intended to disclose substances contained in THAT Corporation's 2181xL-U series integrated circuits. The table below lists Materials and Substances included in the Joint Industry Guide (JIG) - Material Composition Declaration Guide, released on September 19, 2003. This covers all materials defined in Article 4.1 of the European Directive 2002/95/EC on the restriction of the use of certain hazardous substances in electrical and electronic equipment (RoHS Directive).

Materials Declaration

Leadframe Plating: NiPdAu				Percent by weight of homogenous material ¹						
Controlled Chemicals		Threshold Limits		IC itself	Shipping Container					
		RoHS	JIG		Box	Bag	Tube	End Plugs		
Cadmium	Elemental	0.01%	0.0075%, and not intentionally added	<0.00003%	ND ²	ND	ND	ND		
	Cd Compounds			ND	ND	ND	ND	ND		
Lead	Elemental	0.10%	0.10%, and not intentionally added	<0.03%	ND	ND	ND	ND		
	Pb Compounds			ND	ND	ND	ND	ND		
Mercury	Elemental			<0.0001%	ND	ND	ND	ND		
	Hg Compounds			ND	ND	ND	ND	ND		
Hexavalent Chromium	Elemental			<0.00001%	ND	ND	ND	ND		
	Cr ₆ Compounds			ND	ND	ND	ND	ND		
Polybrominated biphenyls (PBB)						ND	ND	ND	ND	ND
Polybrominated diphenylethers (PBDE)						ND	ND	ND	ND	ND
Polychlorinated biphenyls (PCB)						ND	ND	ND	ND	ND
Polychlorinated naphthalenes (PCN)						ND	ND	ND	ND	ND
Polychlorinated terphenyls (PCT)				ND	ND	ND	ND	ND		
Chlorinated parafins (CP)		Not Regulated	Not intentionally added	ND	ND	ND	ND	ND		
Other Chlorinated Compounds				<0.0003%	ND	ND	ND	ND		
Azo Compounds				ND	ND	ND	ND	ND		
Tributyltin compounds				ND	ND	ND	ND	ND		
Triphenyltin compounds				ND	ND	ND	ND	ND		
Other brominated organic compounds		Not Regulated	0.01%	ND	ND	ND	ND	ND		
Antimony				ND	ND	ND	ND	ND		
Other antimony compounds				ND	ND	ND	ND	ND		
Asbestos				ND	ND	ND	ND	ND		
Polyvinyl chloride (PVC) and blends				ND	ND	ND	<0.001% of Vinyl Chloride			

Notes

1. A material is homogeneous if its compound concentration (as % wt) is not changed by mechanical disjoining (cutting, grinding, etc.). For example, in an integrated circuit, the homogenous materials would be the ink, mold compound, gold wires, die, die attach epoxy, base lead frame material and lead frame surface finish. Laser-marked parts may not include ink.
2. ND - None Detected.

Disclaimer

This information has been collected from THAT Corporation's manufacturing facilities and our worldwide supply chain. To the best of our knowledge, it is correct as of the date indicated on this page. However, we cannot guarantee its completeness or accuracy as some information has been derived from data sources outside the company.